



102385616

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party (ies): **3-7-03**
1) Markus Kirchoff
(Additional name(s) of conveying party (ies) attached) Yes No

2. Name and address of receiving party (ies):
Name: SEMICONDUCTOR300 GmbH & Co. KG
Street Address: Königsbrücker Strasse 150
City: Dresden
State: Germany
ZIP: 01099
Additional name(s) & address (es) attached Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other

Execution Date: December 3, 2001

4. Application number(s) or patent number(s):
If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s) 09/954,414
B. Patent No.(s)
Additional numbers attached Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Lerner and Greenberg
Street Address: P.O. Box 2480
City: Hollywood
State: FL
ZIP: 33022

6. Total number of applications and patents involved:

1

7. Total fee (37 CFR 3.4).....\$ 40.00

Enclosed
 Authorized to be charged to deposit account

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9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document

DENISE LETTAU

March 3, 2003

Name of Person Signing

Signature

Date

Total number of pages including cover sheet, attachments, and document:

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Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

PATENT
REEL: 013815 FRAME: 0748

ASSIGNMENT

WHEREAS I, Markus KIRCHHOFF, residing at Steinstr. 9, 01458 Ottendorf-Okrilla, Germany, have invented certain new and useful improvements in a

“Method of filling gaps on a semiconductor wafer”

for which an application for Letters Patent of the United States of America was executed on the date of execution of this assignment;

WHEREAS, SEMICONDUCTOR300 GmbH & Co. KG, a German corporation doing business at Koenigsbruecker Str. 180, 01099 Dresden, Germany is desirous of acquiring the entire interest in the invention, and in any and all Letters Patent of the United States that may be obtained therefor;

NOW, THEREFORE, be it known that for and in consideration of my employment by the said corporation and other valuable consideration, the receipt and sufficiency whereof are hereby acknowledged, I have sold, assigned and transferred, and by these presents do sell, assign and transfer unto the said corporation, its legal representative, successors and assigns, the full and exclusive right to the said invention as fully set forth and described in the above-mentioned application, and to the application and any and all divisions and continuations thereof, and any and all Letters Patent of the United States which may be granted therefore, and any and all reissues of the Letters Patent, the same to be held and enjoyed by the said corporation, its legal representatives, successors and assigns, to the full end of the term for which the Letters Patent may be granted or may be reissued or extended, as fully and entirely as the same would have been held by me had this assignment and sale not been made.

AND I hereby authorize the Commissioner of Patents to issue any and all Letters Patent of the United States on the invention or resulting from the application and from any and all divisions and continuations thereof of the said corporation as the assignee of the entire right, title and interest in and to the same.

IN TESTIMONY WHEREOF, I have hereunto set my hand and seal this *Third* day of *December*, 2001.

In the presence of:

Christiane Weidmann

J. G. G. G.

Markus Kirchhoff (L.S.)
Markus KIRCHHOFF